



**PCN# 20150306000A
Datasheet update for OPA192
Data Sheet Change Notification**

The reason for this addendum is to include an update previously omitted to OPA192datasheet. Details highlight on the pages below.

Date: 3/31/2015
To: MOUSER PCN

Dear Customer:

This is a notice of change to a product data sheet for a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20150306000A
Data Sheet Change Notification
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
OPA192ID	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20150306000A	PCN Date:	03/31/2015
Title:	Datasheet update for OPA192		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	06/31/2015		
Change Type:			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site	
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material	
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site	
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials	
		<input type="checkbox"/> Wafer Fab Process	

PCN Details

Description of Change:

The product datasheet(s) is being updated as summarized below.

The following change history provides further details:

This information was previously communicated in 20150306000.



OPA192, OPA2192, OPA4192

SBOS620B – DECEMBER 2013 – REVISED MARCH 2015

www.ti.com

Changes from Revision A (January 2014) to Revision B

Page

• Added ESD Ratings and Recommended Operating Conditions tables, and <i>Parameter Measurement Information, Application and Implementation, Power-Supply Recommendations, and Device and Documentation Support</i> sections, and moved existing sections	1
• Changed all OPA192 and OPA2192 packages to production data.....	1
• Changed package names to latest standard; changed all MSOP to VSSOP, SO to SOIC, and SOT23 to SOT	1
• Deleted DCK package pin configuration.....	4
• Added thermal information for OPA192 DBV and DGK packages.....	6
• Added OPA2192 and OPA4192 Thermal Information tables	7
• Added rows with additional test conditions to input offset voltage parameter.....	7
• Changed Input offset voltage drift parameter	7
• Changed CMRR test conditions	8
• Added rows with additional test conditions to input offset voltage parameter.....	9
• Changed Input offset voltage drift parameter	9
• Changed PSSR parameter	9
• Changed CMRR test conditions	9
• Added <i>Output</i> section	10
• Added typical characteristic curves to Table 1	11
• Added $T_A = 25^\circ\text{C}$ to Typical Characteristics condition line	11
• Added nine new histogram plots from Figure 2 to Figure 10	12
• Changed Figure 11 to show more units	12
• Changed Figure 19	14
• Added text to <i>Application Information</i> section	30
• Changed text in <i>Layout Guidelines</i> section	34

This is updated information:



OPA192, OPA2192, OPA4192
SBOS620C – DECEMBER 2013 – REVISED MARCH 2015

www.ti.com

Changes from Revision B (March 2014) to Revision C	Page
• Added CDM row for OPA2192, OPA4192 in ESD Ratings table	6
• Changed input offset voltage values for $V_{CM} \geq (V+) - 1.5$ V test condition	7
• Changed Input offset voltage parameter typical specs for $V_{CM} = (V+) - 1.5$ V test conditions	7
• Changed test conditions for dV_{OS}/dT parameter	7
• Changed input offset voltage max values and test conditions for $V_{CM} = (V+) - 3$ V test condition	9
• Changed input offset voltage values and test conditions for $V_{CM} = (V+) - 1.5$ V test condition	9
• Changed Input offset voltage parameter typical specs for $V_{CM} = (V+) - 1.5$ V test conditions	9
• Changed test conditions for dV_{OS}/dT parameter	9
• Added text to last bullet of <i>Layout Guidelines</i> section.....	34

The datasheet number will be changing.

Device Family	Change From:	Change To:
OPA192	SBOS620A	SBOS620B
OPA192	SBOS620B	SBOS620C

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/opa192>

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

To more accurately reflect device characteristics.

Changes to product identification resulting from this PCN:

None.

Product Affected:

OPA192ID	OPA192IDR
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com